Surface Mount Fuse, 3.2 x 1.6 mm, Super-Quick-Acting FF, 63 VDC, low impedance

new



UL 248-14 · 125 VAC · 63 VDC · Super-Quick-Acting FF

Description
- Low impedance, very fast opening time
- Complement USF 1206 with lower current ratings

Standards
- UL 248-14
- CSA C22.2 no. 248.14

Approvals
- UL File Number: E41599

Applications
- Semiconductor Protection

References
Packaging Details

Weblinks
pdf, html, General Product Information, Approvals, RoHS, CHINA-RoHS, e-Store, SCHURTER-Stock-Check, Distributor-Stock-Check

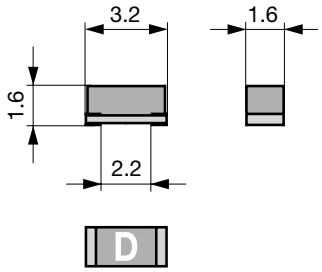
Technical Data

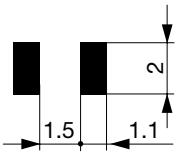
Rated Voltage	125 VAC, 63 VDC
Rated Current	0.16 - 0.25 A
Breaking Capacity	100 A
Characteristic	Super-Quick-Acting FF
Mounting	PCB,SMT
Admissible Ambient Air Temp.	-55 °C to 90 °C
Climatic Category	55/090/21 acc. to IEC 60068-1
Material: Housing	Epoxyd Glass, UL 94V-0
Material: Terminals	Gold-Plated Copper Alloy
Unit Weight	0.0133 g
Storage Conditions	0 °C to 60 °C, max. 70% r.h.
Product Marking	Letter (see variants)

Soldering Methods	Reflow
Solderability	245 °C / 3 sec acc. to IEC 60068-2-58, Test Td
Resistance to Soldering Heat	260 °C / 30 sec acc. to IPC/JEDEC J-STD-020D, Level 1
Terminal Strength	MIL-STD-202, Method 211A Deflection of board 1 mm for 1 minute
Resistance to Solvents	MIL-STD-202, Method 215A

Dimensions

3.2 mm





Soldering pads

Pre-Arcing Time

Rated Current In	1.0 x In min.	2.5 x In max.	10.0 x In min.	10.0 x In max.
0.16 A - .25 A	4 h	5 s	0.1 ms	1 ms

Variants

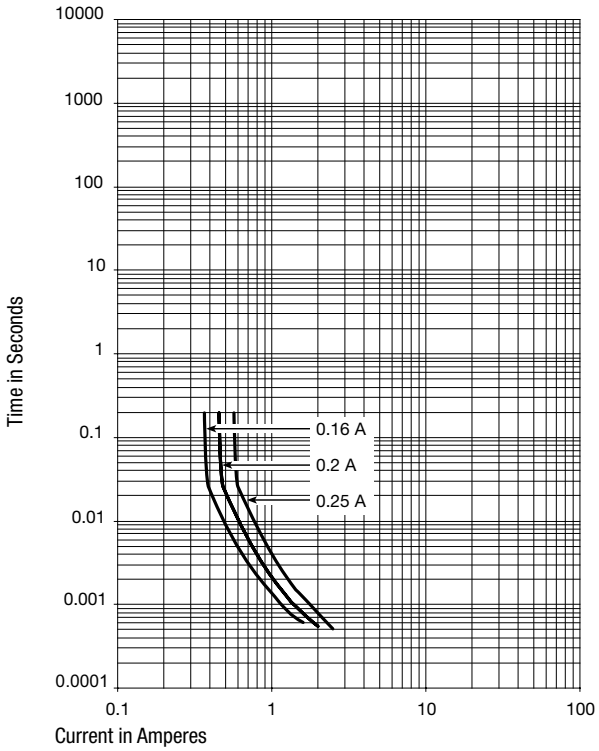
Rated Current [A]	Rated Voltage [VAC]	Rated Voltage [VDC]	Marking	Breaking Capacity	Voltage Drop 1.0 In typ. [mV]	Cold Resistance typ. [mΩ]	Melting I²t 8.0 In typ. [A²s]	c UL us	Order Number
0.16	125	63	0.16	1)	95	510	0.0015	●	3413.0008.xx
0.2	125	63	C	1)	87	365	0.0029	●	3413.0009.xx
0.25	125	63	D	1)	75	255	0.0032	●	3413.0010.xx

1) 100 A @ 125 VAC, 100 A @ 63 VDC

Packaging Unit

.xx = .11 Blister Tape (100 pcs.)
.xx = .22 Blister Tape 18 cm Reel (1000 pcs.)
.xx = .24 Blister Tape 18 cm Reel (5000 pcs.)
.xx = .26 Blister Tape 33 cm Reel (15000 pcs.)

Time-Current-Curves



SCHURTER ELECTRONIC COMPONENTS
The specifications, descriptions and illustrations indicated in this document are based on current information. All content is subject to modifications and amendments.